Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	160
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	3.22 E-01	52944
SiO2 Filler	86	3.46 E+00	569152
Phenol Resin	5	2.01 E-01	33090
Antimony_Sb2O3	0.4	1.61 E-02	2647
Brominated Resin	0.4	1.61 E-02	2647
Carbon Black	0.2	8.04 E-03	1324

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.13 E+00	186127
Ni	3	3.53 E-02	5804
Si	0.65	7.64 E-03	1258
Mg	0.15	1.76 E-03	290

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.81 E-02	4627

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.37 E-02	5551

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.45 E-03	1227

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	7.53 E-01	123971

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.48 E-02	2429
Ag Filler	74	4.20 E-02	6912

Package Totals

Weight (g)	PPM
6.08 E+00	1000000

STS-S-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	160
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	3.22 E-01	52944
SiO2 Filler	86	3.46 E+00	569152
Phenol Resin	5	2.01 E-01	33090
Antimony_Sb2O3	0.4	1.61 E-02	2647
Brominated Resin	0.4	1.61 E-02	2647
Carbon Black	0.2	8.04 E-03	1324

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.13 E+00	186127
Ni	3	3.53 E-02	5804
Si	0.65	7.64 E-03	1258
Mg	0.15	1.76 E-03	290

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.81 E-02	4627

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.87 E-02	4718
Pb	15	5.06 E-03	833

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.45 E-03	1227

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	7.53 E-01	123971

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.48 E-02	2429
Ag Filler	74	4.20 E-02	6912

Package Totals

Weight (g)	PPM
6.08 E+00	1000000

STS-S-A

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc any inaccuracy of such information.

ADI Proprietary

04/07/04